

Freeform Search

Database: US Pre-Grant Publication Full-Text Database
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Term: L56 and (thermometer or probe)

Display: 10 Documents in Display Format: - Starting with Number 1

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DATE: Tuesday, March 15, 2005 [Printable Copy](#) [Create Case](#)

<u>Set</u> <u>Name</u> side by side	<u>Query</u>	<u>Hit</u> <u>Count</u>	<u>Set</u> <u>Name</u> result set
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>			
<u>L57</u>	L56 and (thermometer or probe)	144	<u>L57</u>
<u>L56</u>	L55 and (circuit or board or electronics)	354	<u>L56</u>
<u>L55</u>	L10 and "thermal insulation"	545	<u>L55</u>
<u>L54</u>	L10 and "thermally insulated cavity"	0	<u>L54</u>
<i>DB=USPT; PLUR=YES; OP=ADJ</i>			
<u>L53</u>	L52 and "glue"	1	<u>L53</u>
<u>L52</u>	5109864.pn.	1	<u>L52</u>
<u>L51</u>	L50 and (insulat\$3)	0	<u>L51</u>
<u>L50</u>	5782561.pn.	1	<u>L50</u>
<u>L49</u>	L48 and (insulat\$3)	0	<u>L49</u>
<u>L48</u>	5743647.pn.	1	<u>L48</u>
<i>DB=PGPB; PLUR=YES; OP=ADJ</i>			
<u>L47</u>	L46 and "5"	1	<u>L47</u>
<u>L46</u>	20030169803	1	<u>L46</u>
<u>L45</u>	L44 and "5"	1	<u>L45</u>

<u>L44</u>	20040169803	1	<u>L44</u>
<i>DB=USPT; PLUR=YES; OP=ADJ</i>			
<u>L43</u>	L41 and "curcuit"	0	<u>L43</u>
<u>L42</u>	L41 and (insulat\$3)	0	<u>L42</u>
<u>L41</u>	3903744.pn.	1	<u>L41</u>
<u>L40</u>	5420757.pn.	1	<u>L40</u>
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>			
<u>L39</u>	(microprocessor chip) same (epoxy)	19	<u>L39</u>
<u>L38</u>	(microprocessor package) same (epoxy)	5	<u>L38</u>
<u>L37</u>	insulat\$3 embed\$2 processor	0	<u>L37</u>
<u>L36</u>	encapsulat\$3 processor	38	<u>L36</u>
<u>L35</u>	processor encapsulat3 epoxy	0	<u>L35</u>
<u>L34</u>	processor embed\$3 epoxy	1	<u>L34</u>
<u>L33</u>	microprocessor encapsulat\$3 epoxy	0	<u>L33</u>
<u>L32</u>	circuit encapsulat\$3 epoxy	18	<u>L32</u>
<u>L31</u>	circuit embedded epoxy	2	<u>L31</u>
<u>L30</u>	microprocessor embedded epoxy or microprocessor encapsulated epoxy	0	<u>L30</u>
<u>L29</u>	epoxy housing	124	<u>L29</u>
<u>L28</u>	L10 and "epoxy housing"	2	<u>L28</u>
<u>L27</u>	L24 and "epoxy housing"	0	<u>L27</u>
<u>L26</u>	L24 and (encapsulat\$3 board or encapsulat\$3 electronics)	4	<u>L26</u>
<u>L25</u>	L24 and (thermometer or temperature sens\$3)	15	<u>L25</u>
<u>L24</u>	insulat\$3 circuit board or insulat\$3 printed board or insulat\$3 microprocessor	709	<u>L24</u>
<u>L23</u>	(circuit or microprocessor) same (epoxy insulat\$3)	229	<u>L23</u>
<u>L22</u>	L10 and (epoxy insulat\$3)	9	<u>L22</u>
<u>L21</u>	L10 and (low thermal conductI\$5)	534	<u>L21</u>
<u>L20</u>	L10 and "plastic housing"	73	<u>L20</u>
<u>L19</u>	L10 and "data logger"	81	<u>L19</u>
<u>L18</u>	(data logger) same (thermal\$2 insulat\$3 housing)	0	<u>L18</u>
<u>L17</u>	L10 and (thermal\$2 insulat\$2 housing)	18	<u>L17</u>
<u>L16</u>	L1 and (thermal\$2 insulat\$3 housing)	0	<u>L16</u>
<u>L15</u>	L14 and (insulat\$3 housing)	28	<u>L15</u>
<u>L14</u>	L10 and "digital"	4200	<u>L14</u>
<u>L13</u>	L12 and "digital"	49	<u>L13</u>
<u>L12</u>	L10 and (waterproof\$2 housing or seal\$3 housing)	145	<u>L12</u>
<u>L11</u>	L10 and "pacifier"	46	<u>L11</u>
<u>L10</u>	374/\$	25902	<u>L10</u>
<u>L9</u>	L8 and "waterproof"	60	<u>L9</u>
<u>L8</u>	L7 and "thermometer"	5616	<u>L8</u>
<u>L7</u>	374/\$	25902	<u>L7</u>

DB=PGPB,USPT,USOC,EPAB,JPAB; PLUR=YES; OP=ADJ

<u>L6</u>	L5 and (waterproof or seal)	85	<u>L6</u>
<u>L5</u>	L4 and (cook\$3 or food or meat or wine)	288	<u>L5</u>
<u>L4</u>	(374/208,159;116/216,200)[CCLS]	3076	<u>L4</u>
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>			
<u>L3</u>	cooking thermometer	80	<u>L3</u>
<i>DB=JPAB; PLUR=YES; OP=ADJ</i>			
<u>L2</u>	01032131	1	<u>L2</u>
<u>L1</u>	10318542	1	<u>L1</u>

END OF SEARCH HISTORY

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Term:
L26 and "O-ring"

Display: 10 **Documents in Display Format:** - **Starting with Number** 1

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DATE: Tuesday, March 15, 2005 [Printable Copy](#) [Create Case](#)

Set Name Query

side by side

Hit Count Set Name

result set

DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ

<u>L28</u>	L26 and "O-ring"	49	<u>L28</u>
<u>L27</u>	L26 and "gasket"	301	<u>L27</u>
<u>L26</u>	L1 and "screw"	3280	<u>L26</u>

DB=USPT; PLUR=YES; OP=ADJ

<u>L25</u>	L23 and "screw"	0	<u>L25</u>
<u>L24</u>	L23 and "screw" and "gasket"	0	<u>L24</u>
<u>L23</u>	5005986.pn.	1	<u>L23</u>
<u>L22</u>	6367974.pn.	1	<u>L22</u>

DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ

<u>L21</u>	heat resistant glue or thermally resistant glue	78	<u>L21</u>
<u>L20</u>	L1 and (thermal\$2 resistant glue)	0	<u>L20</u>
<u>L19</u>	L1 and "heat resistant glue"	0	<u>L19</u>
<u>L18</u>	foam insulated housing	4	<u>L18</u>
<u>L17</u>	L1 and (insulat\$3 foam)	28	<u>L17</u>
<u>L16</u>	L1 and "foam"	591	<u>L16</u>

DB=USPT; PLUR=YES; OP=ADJ

<u>L15</u>	L12 and "foam"	58	<u>L15</u>
<u>L14</u>	L12 and "insulation foam"	1	<u>L14</u>
<u>L13</u>	L12 and "insulation"	248	<u>L13</u>
<u>L12</u>	374/208	1586	<u>L12</u>
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>			
<u>L11</u>	5741072[uref]	2	<u>L11</u>
<u>L10</u>	L9 and (probe or thermometer)	197	<u>L10</u>
<u>L9</u>	L1 and "heat resistant"	475	<u>L9</u>
<u>L8</u>	L1 and "thermally insulated jacket"	0	<u>L8</u>
<u>L7</u>	L1 and (thermal\$2 insulat\$3)	1338	<u>L7</u>
<u>L6</u>	5100244[uref]	3	<u>L6</u>
<u>L5</u>	L1 and (thermally insulated enclosure or thermally insulated housing)	27	<u>L5</u>
<u>L4</u>	L3 and (thermometer or probe)	145	<u>L4</u>
<u>L3</u>	L2 and (circuit or board or electronics or processor)	364	<u>L3</u>
<u>L2</u>	L1 and "thermal insulation"	545	<u>L2</u>
<u>L1</u>	374/\$	25902	<u>L1</u>

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DATE: Tuesday, March 15, 2005 [Printable Copy](#) [Create Case](#)

Set Name Query

side by side

Hit Count Set Name

result set

DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ

<u>L34</u>	L32 and "threaded connection"	122	<u>L34</u>
<u>L33</u>	L31 and "threaded connection"	0	<u>L33</u>
<u>L32</u>	L1 and "threaded"	2837	<u>L32</u>

DB=USPT; PLUR=YES; OP=ADJ

<u>L31</u>	L29 and "ring"	1	<u>L31</u>
<u>L30</u>	L29 and "screw"	0	<u>L30</u>
<u>L29</u>	6431110.pn.	1	<u>L29</u>

DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ

<u>L28</u>	L26 and "O-ring"	49	<u>L28</u>
<u>L27</u>	L26 and "gasket"	301	<u>L27</u>
<u>L26</u>	L1 and "screw"	3280	<u>L26</u>

DB=USPT; PLUR=YES; OP=ADJ

<u>L25</u>	L23 and "screw"	0	<u>L25</u>
<u>L24</u>	L23 and "screw" and "gasket"	0	<u>L24</u>
<u>L23</u>	5005986.pn.	1	<u>L23</u>
<u>L22</u>	6367974.pn.	1	<u>L22</u>

DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ

<u>L21</u>	heat resistant glue or thermally resistant glue	78	<u>L21</u>
<u>L20</u>	L1 and (thermal\$2 resistant glue)	0	<u>L20</u>
<u>L19</u>	L1 and "heat resistant glue"	0	<u>L19</u>
<u>L18</u>	foam insulated housing	4	<u>L18</u>
<u>L17</u>	L1 and (insulat\$3 foam)	28	<u>L17</u>
<u>L16</u>	L1 and "foam"	591	<u>L16</u>

DB=USPT; PLUR=YES; OP=ADJ

<u>L15</u>	L12 and "foam"	58	<u>L15</u>
<u>L14</u>	L12 and "insulation foam"	1	<u>L14</u>
<u>L13</u>	L12 and "insulation"	248	<u>L13</u>
<u>L12</u>	374/208	1586	<u>L12</u>

DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ

<u>L11</u>	5741072[uref]	2	<u>L11</u>
<u>L10</u>	L9 and (probe or thermometer)	197	<u>L10</u>
<u>L9</u>	L1 and "heat resistant"	475	<u>L9</u>
<u>L8</u>	L1 and "thermally insulated jacket"	0	<u>L8</u>
<u>L7</u>	L1 and (thermal\$2 insulat\$3)	1338	<u>L7</u>
<u>L6</u>	5100244[uref]	3	<u>L6</u>
<u>L5</u>	L1 and (thermally insulated enclosure or thermally insulated housing)	27	<u>L5</u>
<u>L4</u>	L3 and (thermometer or probe)	145	<u>L4</u>
<u>L3</u>	L2 and (circuit or board or electronics or processor)	364	<u>L3</u>
<u>L2</u>	L1 and "thermal insulation"	545	<u>L2</u>
<u>L1</u>	374/\$	25902	<u>L1</u>

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IBM Technical Disclosure Bulletins

Term: (microprocessor chip) same (epoxy)

Display: 10 Documents in Display Format: - Starting with Number 1

Generate: ☐ Hit List ☒ Hit Count ☐ Side by Side ☐ Image

Search
Clear
Interrupt

Search History

DATE: Tuesday, March 15, 2005 [Printable Copy](#) [Create Case](#)

<u>Set</u> <u>Name</u>	<u>Query</u>	<u>Hit</u> <u>Count</u>	<u>Set</u> <u>Name</u> result set
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>			
<u>L39</u>	(microprocessor chip) same (epoxy)	19	<u>L39</u>
<u>L38</u>	(microprocessor package) same (epoxy)	5	<u>L38</u>
<u>L37</u>	insulat\$3 embed\$2 processor	0	<u>L37</u>
<u>L36</u>	encapsulat\$3 processor	38	<u>L36</u>
<u>L35</u>	processor encapsulat3 epoxy	0	<u>L35</u>
<u>L34</u>	processor embed\$3 epoxy	1	<u>L34</u>
<u>L33</u>	microprocessor encapsulat\$3 epoxy	0	<u>L33</u>
<u>L32</u>	circuit encapsulat\$3 epoxy	18	<u>L32</u>
<u>L31</u>	circuit embedded epoxy	2	<u>L31</u>
<u>L30</u>	microprocessor embedded epoxy or microprocessor encapsulated epoxy	0	<u>L30</u>
<u>L29</u>	epoxy housing	124	<u>L29</u>
<u>L28</u>	L10 and "epoxy housing"	2	<u>L28</u>
<u>L27</u>	L24 and "epoxy housing"	0	<u>L27</u>
<u>L26</u>	L24 and (encapsulat\$3 board or encapsulat\$3 electronics)	4	<u>L26</u>
<u>L25</u>	L24 and (thermometer or temperature sens\$3)	15	<u>L25</u>

<u>L24</u>	insulat\$3 circuit board or insulat\$3 printed board or insulat\$3 microprocessor	709	<u>L24</u>
<u>L23</u>	(circuit or microprocessor) same (epoxy insulat\$3)	229	<u>L23</u>
<u>L22</u>	L10 and (epoxy insulat\$3)	9	<u>L22</u>
<u>L21</u>	L10 and (low thermal conductI\$5)	534	<u>L21</u>
<u>L20</u>	L10 and "plastic housing"	73	<u>L20</u>
<u>L19</u>	L10 and "data logger"	81	<u>L19</u>
<u>L18</u>	(data logger) same (thermal\$2 insulat\$3 housing)	0	<u>L18</u>
<u>L17</u>	L10 and (thermal\$2 insulat\$2 housing)	18	<u>L17</u>
<u>L16</u>	L1 and (thermal\$2 insulat\$3 housing)	0	<u>L16</u>
<u>L15</u>	L14 and (insulat\$3 housing)	28	<u>L15</u>
<u>L14</u>	L10 and "digital"	4200	<u>L14</u>
<u>L13</u>	L12 and "digital"	49	<u>L13</u>
<u>L12</u>	L10 and (waterproof\$2 housing or seal\$3 housing)	145	<u>L12</u>
<u>L11</u>	L10 and "pacifier"	46	<u>L11</u>
<u>L10</u>	374/\$	25902	<u>L10</u>
<u>L9</u>	L8 and "waterproof"	60	<u>L9</u>
<u>L8</u>	L7 and "thermometer"	5616	<u>L8</u>
<u>L7</u>	374/\$	25902	<u>L7</u>
<i>DB=PGPB,USPT,USOC,EPAB,JPAB; PLUR=YES; OP=ADJ</i>			
<u>L6</u>	L5 and (waterproof or seal)	85	<u>L6</u>
<u>L5</u>	L4 and (cook\$3 or food or meat or wine)	288	<u>L5</u>
<u>L4</u>	(374/208,159;116/216,200)[CCLS]	3076	<u>L4</u>
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>			
<u>L3</u>	cooking thermometer	80	<u>L3</u>
<i>DB=JPAB; PLUR=YES; OP=ADJ</i>			
<u>L2</u>	01032131	1	<u>L2</u>
<u>L1</u>	10318542	1	<u>L1</u>

END OF SEARCH HISTORY